

# [GOLD BUMP STRUCTURE AND FABRICATING METHOD THEREOF]

## Abstract

A flip-chip gold bump structure and a method of fabricating thereof are disclosed. The structure includes a nickel layer formed on a gold bump formed on a chip, and a copper layer formed on the nickel layer for forming a Ni/Cu barrier layer. Because of the formation of the Ni/Cu layer which prevents the interaction of the gold bump and the solder, the fragile connecting point resulting from the rapid interaction of the Au-Sn can be eliminated.